

Actron Technology

(8255.TT)



Investor Conference

Speakers:

- 吳憲忠 George Wu: President / Spokesperson
- 黃錫欽 Jason Huang: VP of Sales & Marketing / Deputy Spokesperson
- 鍾曉瑩 Mia Chung : Special assistance / Investor Relations

May 26, 2026

Agenda



1. Financial Highlight
2. Global Automobile Sales
3. Q & A

Statements of Comprehensive Income

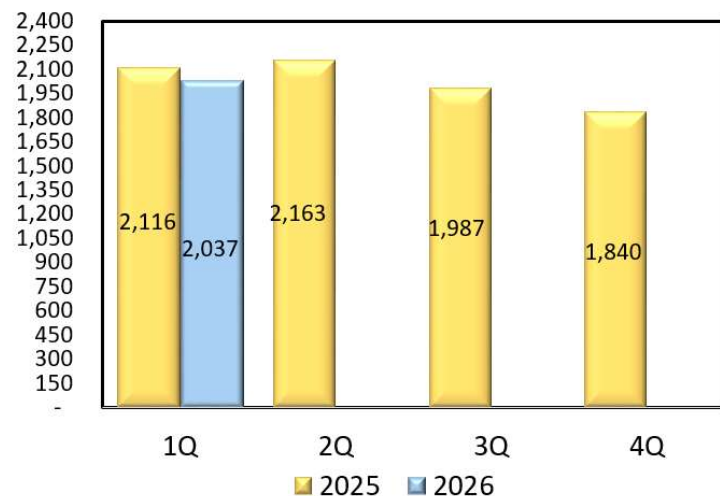
Statements of Comprehensive Income

Amount : NT\$ Million

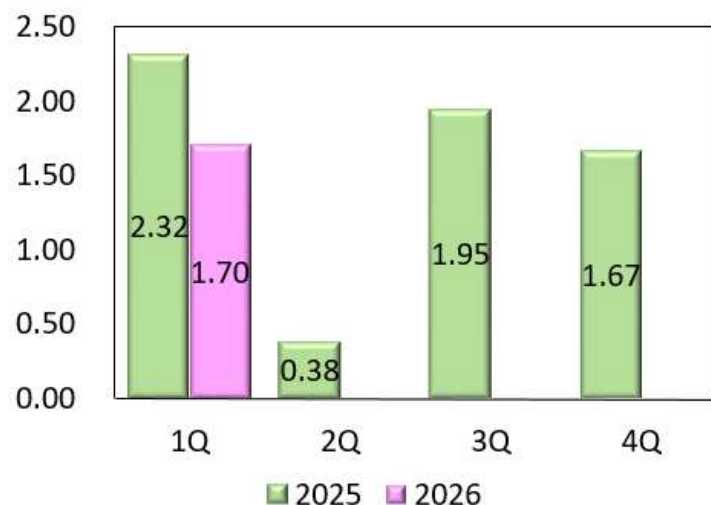
	1Q2026		4Q2025		1Q2025		1Q26 Over 4Q25	1Q26 Over 1Q25
	Amount	%	Amount	%	Amount	%	%	%
Net operating revenue	2,037	100.00	1,840	100.00	2,116	100.00	10.71%	-3.73%
Operating costs	1,488	73.05	1,352	73.48	1,507	71.22	10.06%	-1.26%
Gross profit	549	26.95	488	26.52	609	28.78	12.50%	-9.85%
Operating expenses	419	20.57	428	23.26	370	17.49	-2.10%	13.24%
Operating income	130	6.38	60	3.26	239	11.29	116.67%	-45.61%
Non-operating income and expenses	40	1.96	66	3.59	69	3.26	-160.61%	-42.03%
Profit before tax	170	8.35	126	6.85	308	14.56	34.92%	-44.81%
Net profit attributable to: Owners of the parent company	173	8.49	170	9.24	236	11.15	1.76%	-26.69%
EPS(NT\$)	1.70		1.67		2.32		1.80%	-26.72%

Financial Highlight

Unit:NT\$M Quarterly revenue

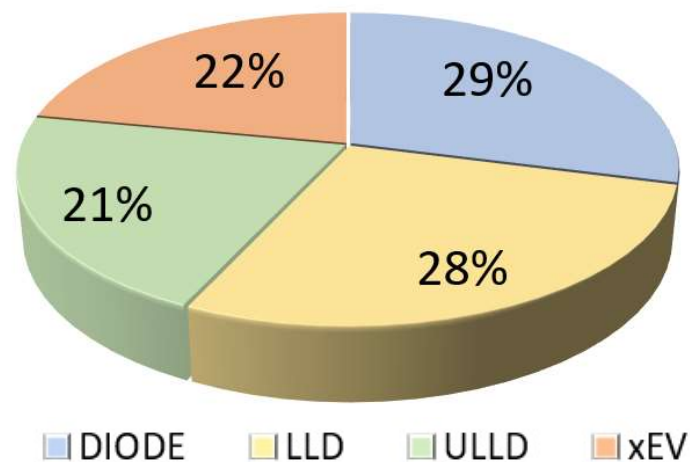


Quarterly EPS

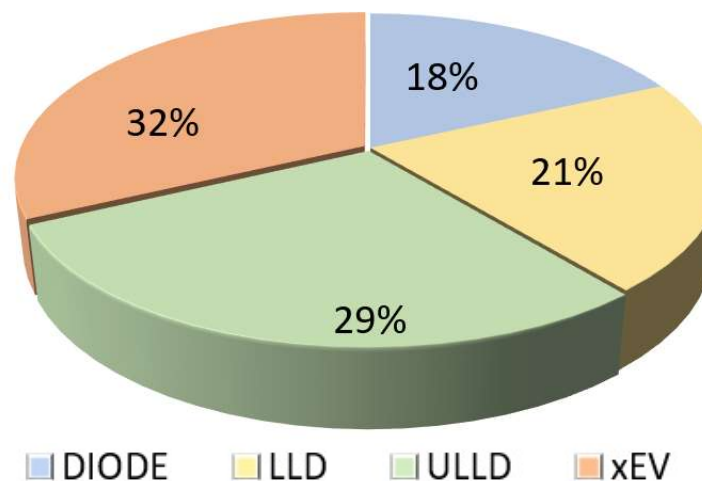


Sales Contribution by Products

2025



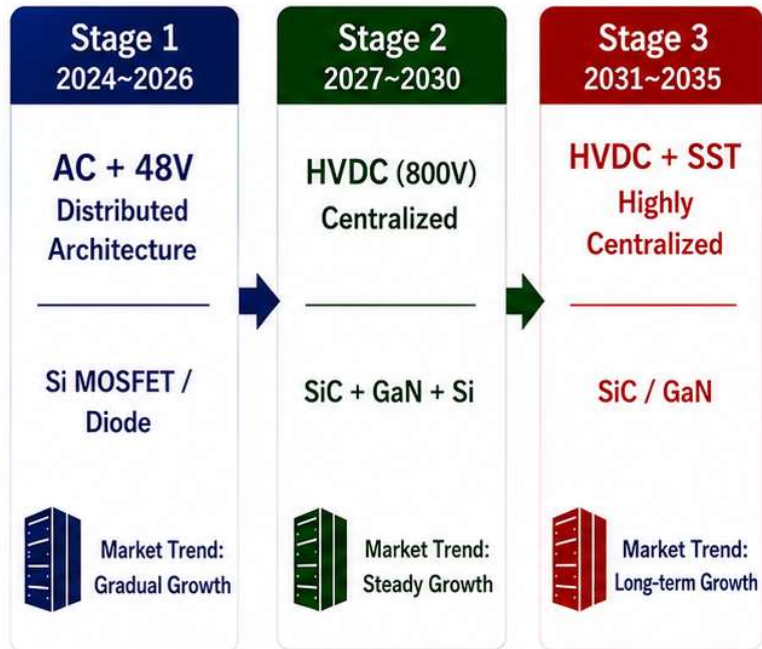
2026(F)



Actron AI Power Strategy for HVDC / SST



1. Architecture Evolution Trend



2. Power Component Strategy



PSU / BBU (AI Data Center)

Current: Discrete Dominant
TO-220 / TO-247 / TO-263

Future: Miniaturization Packaging Trend
TOLL / TOLT / QDPAK

Volume Constraint → Module Not Always Optimal



SST / HVDC (Next-Gen Architecture)

Core Technology: SiC (High Voltage)
Solution Approach: Module Dominant

High Voltage / High Power / High Reliability
→ Module as the Core Solution

3. Medium-Term Business Opportunities



AI Data Centers, HVDC,
SST, and ESS Applications
Drive Market Demand Growth

Our Opportunities

- ✓ From Discrete to High-Value Module Extension
- ✓ Focus on High Voltage / High Power and High Reliability Applications
- ✓ Leverage Next-Gen Architecture Upgrades
- ✓ Capture Long-Term Growth Opportunities Brought by These Trends

4. Key Enablers and Major Applications

Key Enablers



AI Servers
Power Demand



HVDC
Infrastructure
Development



ESS
Demand
Expansion



Motor Drive
Efficiency
Improvement



SST and Power Grid
Modernization

Major Applications



AI Data Centers



EV Charging
Infrastructure



Renewable
Energy



Industrial
Automation



UPS / ESS



Actron IEBU will continue to deploy SiC technology and high-voltage applications, leveraging AI and HVDC trends to capture long-term growth opportunities.

Complete Power Semiconductor Portfolio

Power Module-Focused Solutions for AI-HVDC, PSU & Industrial Systems



POWER DISCRETE

Si / SiC / GaN

Standard & Advanced Packages

- TO-247
- TOLL
- TOLT*
- QDPAK*

*In Development

Optimized for efficiency, thermal performance & compact design

POWER MODULE – CORE FOR AI & HVDC SYSTEMS

INDUSTRIAL PLATFORMS

AEA
(Easy 1B)

Cost-effective, reliable

AEB
(Easy 2B)

High performance, low inductance

A62
(62mm)

High power / high current

ADP
(ED3)

Compact, standard platform

AUTOMOTIVE PLATFORMS

AEP
(HPD)

High power density

ATS

Compact, thermal optimized

Optimized for AI Power Systems

High Efficiency × High Power Density × High Reliability

AI-HVDC | PSU | BBU | SST | ESS | Motor Drive

INTEGRATED POWER MODULE (IPM)

SD DIP

(Super Mini DIP)

Compact integrated solution

MD DIP

(Mini DIP)

For motor & industrial control

Compact integrated solution for motor & industrial control

Wide Voltage Coverage
650V → 3300V+

Power Module Focus
for AI-HVDC & PSU

Discrete + Module
Complete Solution

Automotive-Grade
Reliability

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Q & A